

SACRIFICIAL PROTECTIVE LAYER FOR IMAGE SENSORS AND METHOD
OF USING

ABSTRACT OF THE DISCLOSURE

A method for protecting an image sensor die is disclosed. The method comprises forming a plurality of image sensor die having micro-lenses onto a semiconductor wafer. Then, a protective layer is formed over the image sensor die. After the protective layer has been formed, and without any removal step of the protective layer, the wafer is diced to separate the plurality of image sensor die. Finally, the image sensor die are mounted onto an integrated circuit package and the protective layer is removed.